

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









RoHS Compliant

Serial ATA Flash Drive

SM210-25 Product Specifications

November 7, 2017

Version 1.9



Apacer Technology Inc.

1F, No.32, Zhongcheng Rd., Tucheng Dist., New Taipei City, Taiwan, R.O.C Tel: +886-2-2267-8000 Fax: +886-2-2267-2261 www.apacer.com

Features:

Compliance with SATA Revision 3.1

- SATA 6.0 Gbps interface
- Backward compatible with SATA 1.5 and 3.0 Gbps interfaces
- ATA-8 command set

Capacity

- 16, 32, 64, 128, 256, 512 GB

Performance*

- Burst read/write: 600 MB/sec

- Sequential read: Up to 510 MB/sec

- Sequential write: Up to 470 MB/sec

- Random read (4K): Up to 83,000 IOPS

- Random write (4K): Up to 79,000 IOPS

Flash Management

- Built-in hardware ECC
- Global Wear Leveling
- Flash bad-block management
- S.M.A.R.T.
- Power Failure Management
- ATA Secure Erase
- TRIM

NAND Flash Type: MLC

• MTBF: >1,000,000 hours

• Endurance (in Terabytes Written: TBW)

- 16 GB: 35 TBW

- 32 GB: 71 TBW

- 64 GB: 142 TBW

- 128 GB: 285 TBW

- 256 GB: 571 TBW

- 512 GB: 1,142 TBW

Temperature Range

Operating:

Standard: 0°C to 70°C Extended: -40°C to 85°C

- Storage: -40°C to 100°C

Supply Voltage

- 5.0 V \pm 5%

Power Consumption*

Active mode: 680 mA

- Idle mode: 75 mA

Connector Type

- 7-pin SATA signal connector
- 15-pin SATA power connector

Form Factor

- 2.5"
- Dimensions with 7mm enclosure:
 100.00 x 69.85 x 6.90, unit: mm
- Dimensions with 9.5mm enclosure: 100.00 x 69.84 x 9.30, unit: mm

Shock & Vibration**

Shock:1,500 G

- Vibration: 15 G

DRAM Cache for Enhanced Random Performance

SATA Power Management Modes

- Thermal Sensor
- Device Sleep
- RoHS Compliant

^{*}Varies from capacities. The values for performances and power consumptions presented are typical and may vary depending on flash configurations or platform settings.

^{**}Non-operating

Table of Contents

1. General Description	ons	3
1.2 Capacity 1.3 Performance 1.4 Pin Assignments		3 3 4
2. Software Interface	e	6
2.2 S.M.A.R.T		6
3. Flash Managemen	t	8
3.2 Bad Block Management 3.3 Global Wear Leveling 3.4 Power Failure Managem 3.5 ATA Secure Erase 3.6 TRIM 3.7 Thermal Sensor 3.8 DEVSLP (DevSleep or D 3.9 SATA Power Manageme	DEVSLP) Mode	
4. Reliability Specific	cations	11
4.2 Mean Time Between Fai 4.3 Certification and Complia	ilures (MTBF) ance	11 11
5. Electrical Specific	cations	13
5.2 Power Consumption		13
6. Physical Characte	eristics	14
7. Product Ordering I	Information	16
7.1 Product Code Designation	ons	16

1. General Descriptions

1.1 Introduction

Apacer's SM210-25 is a well-balanced solid-state disk (SSD) drive with standard form factor and great performance. Designed in SATA 6.0 Gbps interface, the SSD is able to deliver exceptional read/write speed, making it the ideal companion for heavy-loading industrial or server operations.

For data efficiency, the internal controlling unit of the SSD is engineered with DRAM for enhanced random performance. In regard of reliability, the drive comes with various implementations including powerful hardware ECC engine, power saving modes, wear leveling, flash block management, S.M.A.R.T., TRIM, and power failure management.

1.2 Capacity

Capacity specifications of SM210-25 are available as shown in Table 1-1. It lists the specific capacity and the default numbers of heads, sectors and cylinders for each product line.

Table 1-1 Capacity Specifications

Capacity	Total bytes*	Cylinders	Heads	Sectors	Max LBA
16 GB	16,013,942,784	16,383	16	63	31,277,232
32 GB	32,017,047,552	16,383	16	63	62,533,296
64 GB	64,023,257,088	16,383	16	63	125,045,424
128 GB	128,035,676,160	16,383	16	63	250,069,680
256 GB	256,060,514,304	16,383	16	63	500,118,192
512 GB	512,110,190,592	16,383	16	63	1,000,215,216

^{*}Display of total bytes varies from file systems, which means not all of the bytes can be used for storage.

LBA count addressed in the table above indicates total user storage capacity and will remain the same throughout the lifespan of the device. However, the total usable capacity of the SSD is most likely to be less than the total physical capacity because a small portion of the capacity is reserved for device maintenance usages.

1.3 Performance

Performance of SM210-25 is listed below in Table 1-2.

Table 1-2 Performance Specifications

Capacity Performance	16 GB	32 GB	64 GB	128 GB	256 GB	512 GB
Sequential Read* (MB/s)	215	380	510	510	510	490
Sequential Write* (MB/s)	47	100	205	380	350	470
Random Read IOPS** (4K)	26,000	48,000	78,000	81,000	83,000	56,000
Random Write IOPS** (4K)	8,000	24,000	49,000	79,000	79,000	29,000

Note:

Results may differ from various flash configurations or host system setting.

^{**}Notes: 1 GB = 1,000,000,000 bytes; 1 sector = 512 bytes.

^{*}Sequential performance is based on CrystalDiskMark 5.2.1 with file size 1,000MB.

^{**}Random performance measured using IOMeter with Queue Depth 32.

1.4 Pin Assignments

Table 1-3 describes the SFD signal segment, and Table1-4, power segment.

Figure 1-1 SATA Connectors

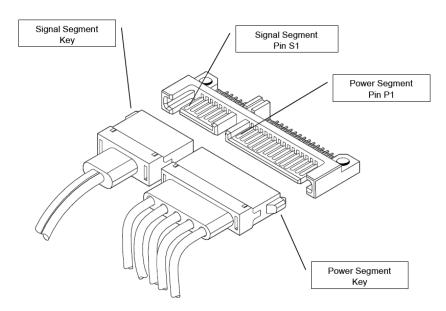


Table 1-3 Signal Segment

Pin	Туре	Description
S1	GND	
S2	RxP	+ Differential Receive Signal
S3	RxN	- Differential Receive Signal
S4	GND	
S5	TxN	- Differential Transmit Signal
S6	TxP	+ Differential Transmit Signal
S7	GND	

Table 1-4 Power Segment

Pin	Signal/Description
P1	Unused (3.3V)
P2	Unused (3.3V)
P3	Device Sleep
P4	Ground
P5	Ground
P6	Ground
P7	5V
P8	5V
P9	5V
P10	Ground
P11	DAS
P12	Ground
P13	Unused (12V)
P14	Unused (12V)
P15	Unused (12V)

Apacer

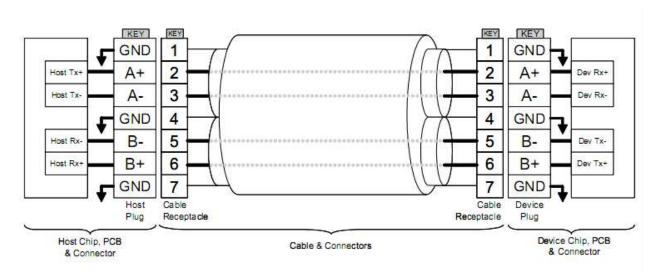


Figure 1-2 SATA Cable/Connector Connection Diagram

The connector on the left represents the Host with TX/RX differential pairs connected to a cable. The connector on the right shows the Device with TX/RX differential pairs also connected to the cable. Notice also the ground path connecting the shielding of the cable to the Cable Receptacle.

2. Software Interface

2.1 Command Set

Table 2-1 summarizes the ATA commands supported by SM210-25.

Table 2-1 Command Set

Code	Command	Code	Command
E5h	Check Power Mode	F6h	Security Disable Password
90h	Execute Diagnostics	F3h	Security Erase Prepare
E7h	Flush Cache	F4h	Security Erase Unit
ECh	Identify Device	F5h	Security Freeze Lock
E3h	Idle	F1h	Security Set Password
E1h	Idle Immediate	F2h	Security Unlock
91h	Initialize Device Parameters	7Xh	Seek
C8h	Read DMA	EFh	Set Features
25h	Read DMA EXT	C6h	Set Multiple Mode
60h	Read FPDMA Queued	E6h	Sleep
47h	Read Log DMA EXT	B0h	S.M.A.R.T.
2Fh	Read Log EXT	E2h	Standby
C4h	Read Multiple	E0h	Standby Immediate
20 or 21h	Read Sector(s)	CAh	Write DMA
40 or 41h	Read Verify Sector(s)	35h	Write DMA EXT
10h	Recalibrate	61h	Write FPDMA Queued
57h	Write Log DMA EXT	3Fh	Write Log EXT
C5h	Write Multiple	30h or 31h	Write Sector(s)

2.2 S.M.A.R.T.

S.M.A.R.T. is an abbreviation for Self-Monitoring, Analysis and Reporting Technology, a self-monitoring system that provides indicators of drive health as well as potential disk problems. It serves as a warning for users from unscheduled downtime by monitoring and displaying critical drive information. Ideally, this should allow taking proactive actions to prevent drive failure and make use of S.M.A.R.T. information for future product development reference.

Apacer devices use the standard SMART command B0h to read data out from the drive to activate our S.M.A.R.T. feature that complies with the ATA/ATAPI specifications. S.M.A.R.T. Attribute IDs shall include initial bad block count, total later bad block count, maximum erase count, average erase count, power on hours and power cycle. When the S.M.A.R.T. Utility running on the host, it analyzes and reports the disk status to the host before the device reaches in critical condition.

Note: Attribute IDs may vary from product models due to various solution design and supporting capabilities.

Apacer memory products come with S.M.A.R.T. commands and subcommands for users to obtain information of drive status and to predict potential drive failures. Users can take advantage of the following commands/subcommands to monitor the health of the drive.

Code	SMART Subcommand
D0h	READ DATA
D1h	READ ATTRIBUTE THRESHOLDS
D2h	Enable/Disable Attribute Autosave
D4h	Execute Off-line Immediate
D5h	Read Log (optional)
D6h	Write Log (optional)
D8h	Enable Operations
D9h	Disable operations
DAh	Return Status

General SMART attribute structure

Byte	Description
0	ID (Hex)
1 – 2	Status flag
3	Value
4	Worst
5*-11	Raw Data

*Byte 5: LSB

SMART attribute ID list

ID (Hex)	Attribute Name
9 (0x09)	Power-on hours
12 (0x0C)	Power cycle count
163 (0xA3)	Max. erase count
164 (0xA4)	Avg. erase count
166 (0xA6)	Total later bad block count
167 (0xA7)	SSD Protect Mode (vendor specific)
168 (0xA8)	SATA PHY Error Count
175 (0xAF)	Bad Cluster Table Count
192 (0xC0)	Unexpected Power Loss Count
194 (0xC2)	Temperature
241 (0xF1)	Total sectors of write

3. Flash Management

3.1 Error Correction/Detection

SM210-25 implements a hardware ECC scheme, based on the BCH algorithm. It can detect and correct up to 72 bits error in 1K bytes.

3.2 Bad Block Management

Current production technology is unable to guarantee total reliability of NAND flash memory array. When a flash memory device leaves factory, it comes with a minimal number of initial bad blocks during production or out-of-factory as there is no currently known technology that produce flash chips free of bad blocks. In addition, bad blocks may develop during program/erase cycles. When host performs program/erase command on a block, bad block may appear in Status Register. Since bad blocks are inevitable, the solution is to keep them in control. Apacer flash devices are programmed with ECC, block mapping technique and S.M.A.R.T to reduce invalidity or error. Once bad blocks are detected, data in those blocks will be transferred to free blocks and error will be corrected by designated algorithms.

3.3 Global Wear Leveling

Flash memory devices differ from Hard Disk Drives (HDDs) in terms of how blocks are utilized. For HDDs, when a change is made to stored data, like erase or update, the controller mechanism on HDDs will perform overwrites on blocks. Unlike HDDs, flash blocks cannot be overwritten and each P/E cycle wears down the lifespan of blocks gradually. Repeatedly program/erase cycles performed on the same memory cells will eventually cause some blocks to age faster than others. This would bring flash storages to their end of service term sooner. Global wear leveling is an important mechanism that levels out the wearing of all blocks so that the wearing-down of all blocks can be almost evenly distributed. This will increase the lifespan of SSDs.

3.4 Power Failure Management

Power Failure Management plays a crucial role when experiencing unstable power supply. Power disruption may occur when users are storing data into the SSD. In this urgent situation, the controller would run multiple write-to-flash cycles to store the metadata for later block rebuilding. This urgent operation requires about several milliseconds to get it done. At the next power up, the firmware will perform a status tracking to retrieve the mapping table and resume previously programmed NAND blocks to check if there is any incompleteness of transmission.

Note: The controller unit of this product model is designed with a DRAM as a write cache for improved performance and data efficiency. Though unlikely to happen in most cases, the data cached in the volatile DRAM might be potentially affected if a sudden power loss takes place before the cached data is flushed into non-volatile NAND flash memory.

3.5 ATA Secure Erase

ATA Secure Erase is an ATA disk purging command currently embedded in most of the storage drives. Defined in ATA specifications, (ATA) Secure Erase is part of Security Feature Set that allows storage drives to erase all user data areas. The erase process usually runs on the firmware level as most of the ATA-based storage media currently in the market are built-in with this command. ATA Secure Erase can securely wipe out the user data in the drive and protects it from malicious attack.

3.6 TRIM

TRIM is a SATA command that helps improve the read/write performance and efficiency of solid-state drives (SSD). The command enables the host operating system to inform SSD controller which blocks contain invalid data, mostly because of the erase commands from host. The invalid will be discarded permanently and the SSD will retain more space for itself.

3.7 Thermal Sensor

Apacer Thermal Sensor is a digital temperature sensor with serial interface. By using designated pins for transmission, storage device owners are able to read temperature data.

3.8 DEVSLP (DevSleep or DEVSLP) Mode

Device Sleep is a feature that allows SATA devices to enter a low power mode by designating pin 44 as DEVSLP signal with an aim to reducing power consumption.



3.9 SATA Power Management

By complying with SATA 6.0 Gb/s specifications, the SSD supports the following SATA power saving modes:

- ACTIVE: PHY ready, full power, Tx & Rx operational
- PARTIAL: Reduces power, resumes in under 10 μs (microseconds)
- SLUMBER: Reduces power, resumes in under 10 ms (milliseconds)
- HIPM: Host-Initiated Power Management
- DIPM: Device-Initiated Power Management
- AUTO-SLUMBER: Automatic transition from partial to slumber.
- Device Sleep (DevSleep or DEVSLP): PHY powered down; power consumption ≤ 5 mW; host assertion time ≤ 10 ms; exit timeout from this state ≤ 20 ms (unless specified otherwise in SATA Identify Device Log).

Note: The behaviors of power management features would depend on host/device settings.

4. Reliability Specifications

4.1 Environmental

Environmental specifications of SM210-25 product are shown in Table 4-1.

Table 4-1 Environmental Specifications

Environment	Specifications	
Tamananatum	0°C to 70°C (Standard); -40°C to 85°C (Extended)	
Temperature	-40°C to 100°C (Non-operating)	
Vibration	Non-operating: Sine wave, 15(G), 10~2000(Hz), Operating: Random, 7.69(Grms), 20~2000(Hz)	
Shock	Non-operating: Acceleration, 1,500 G, 0.5 ms Operating: Peak acceleration, 50 G, 11 ms	

4.2 Mean Time Between Failures (MTBF)

Mean Time Between Failures (MTBF) is predicted based on reliability data for the individual components in SM210-25. The prediction result for SM210-25 is more than 1,000,000 hours.

Note: The MTBF is predicated and calculated based on "Telcordia Technologies Special Report, SR-332, Issue 2" method.

4.3 Certification and Compliance

SM210-25 complies with the following standards:

- CE
- FCC
- RoHS
- MIL-STD-810G

4.4 Endurance

The endurance of a storage device is predicted by TeraBytes Written based on several factors related to usage, such as the amount of data written into the drive, block management conditions, and daily workload for the drive. Thus, key factors, such as Write Amplifications and the number of P/E cycles, can influence the lifespan of the drive.

Table 4-2 Endurance Specifications

Capacity	TeraBytes Written
16 GB	35
32 GB	71
64 GB	142
128 GB	285
256 GB	571
512 GB	1,142

Note:

- The measurement assumes the data written to the SSD for test is under a typical and constant rate.
- The measurement follows the standard metric: 1 TB (Terabyte) = 1,000 GB.
- The estimated values are based on JEDEC Enterprise endurance workload comprised of random data with the payload size distribution with sequential write behavior.

5. Electrical Specifications

5.1 Operating Voltage

Table 5-1 lists the supply voltage for SM210-25.

Table 5-1 Operating Range

Item	Range
Supply Voltage	5V ± 5% (4.75-5.25V)

5.2 Power Consumption

Table 5-2 lists the power consumption for SM210-25.

Table 5-2 Power Consumption

Capacity	16 GB	32 GB	64 GB	128 GB	256 GB	512 GB
Active (mA)	210	240	300	470	680	635
Idle (mA)	75	50	50	50	50	60

^{*}All values are typical and may vary depending on flash configurations or host system settings.

**Active power is an average power measurement performed using CrystalDiskMark with 128KB sequential read/write transfers.

6. Physical Characteristics

6.1 7mm Type Dimensions

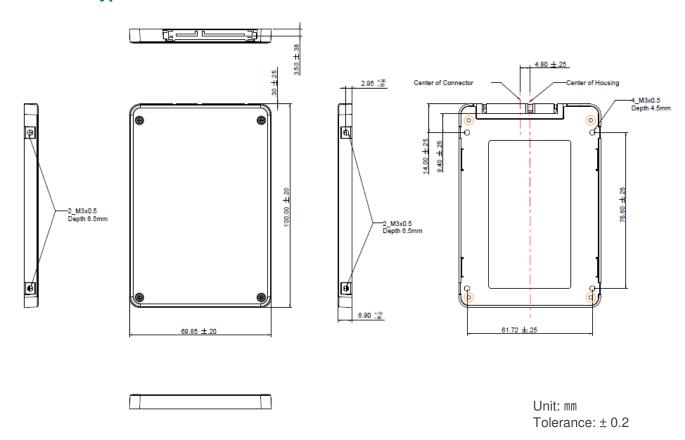
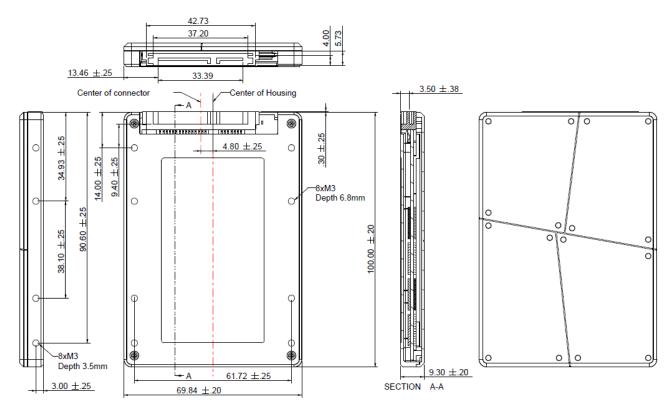


Figure 6-1 7mm Housing Physical Dimensions

6.2 9.5mm Type Dimensions

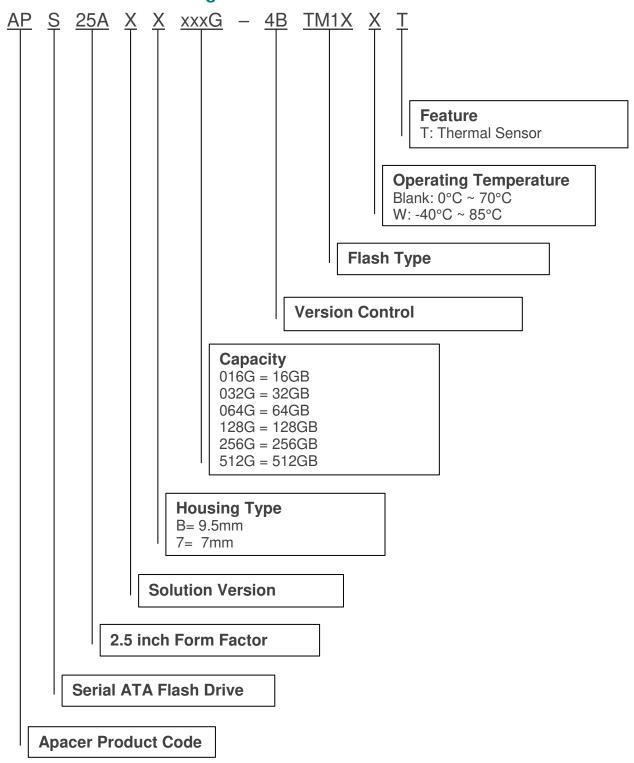


Unit: mm Tolerance: ± 0.2

Figure 6-2 9.5mm Housing Physical Dimensions

7. Product Ordering Information

7.1 Product Code Designations



7.2 Valid Combinations

7.2.1 9.5mm Metal Housing

Capacity	Standard Temperature	Extended Temperature		
16GB	APS25AFB016G-4BTM1T	APS25AFB016G-4BTM1WT		
32GB	APS25AFB032G-4BTM1GT	APS25AFB032G-4BTM1GWT		
64GB	APS25AFB064G-4BTM1GT	APS25AFB064G-4BTM1GWT		
128GB	APS25AFB128G-4BTM1GT	APS25AFB128G-4BTM1GWT		
256GB	APS25AFB256G-4BTM1GT	APS25AFB256G-4BTM1GWT		
512GB	APS25AFB512G-4BTM1GT	APS25AFB512G-4BTM1GWT		

7.2.2 7mm Plastic Housing

Capacity	Standard Temperature	Extended Temperature		
16GB	APS25AF7016G-4BTM1T	APS25AF7016G-4BTM1WT		
32GB	APS25AF7032G-4BTM1GT	APS25AF7032G-4BTM1GWT		
64GB	APS25AF7064G-4BTM1GT	APS25AF7064G-4BTM1GWT		
128GB	APS25AF7128G-4BTM1GT	APS25AF7128G-4BTM1GWT		
256GB	APS25AF7256G-4BTM1GT	APS25AF7256G-4BTM1GWT		
512GB	APS25AF7512G-4BTM1GT	APS25AF7512G-4BTM1GWT		

Note: Valid combinations are those products in mass production or will be in mass production. Consult your Apacer sales representative to confirm availability of valid combinations and to determine availability of new combinations.

Apacer

Revision History

Revision	Description	Date	
1.0	Official release	6/13/2016	
	- Added thermal sensor support		
1.1	- Removed models with no DEVSLP support	7/25/2016	
	- Revised product ordering information		
1.2	- Added 32-256GB support	9/26/2016	
	- Revised product ordering information		
1.3	Revised product ordering information	10/6/2016	
1.4	Updated performance values for 32-256GB	11/10/2016	
1.5	Updated endurance ratings	1/24/2017	
1.6	- Added 16GB support	0/10/0017	
	- Updated product ordering information	2/13/2017	
1.7	- Updated 512GB performance	3/24/2017	
	- Updated product ordering information		
1.8	Updated performance and power consumption for 16GB	4/11/2017	
1.9	Removed altitude spec from 4.1 Environmental	11/7/2017	

Global Presence

Taiwan (Headquarters)

Apacer Technology Inc.

1F., No.32, Zhongcheng Rd., Tucheng Dist., New Taipei City 236, Taiwan R.O.C.

Tel: 886-2-2267-8000 Fax: 886-2-2267-2261 amtsales@apacer.com

Japan

Apacer Technology Corp.

5F, Matsura Bldg., Shiba, Minato-Ku Tokyo, 105-0014, Japan Tel: 81-3-5419-2668

Fax: 81-3-5419-0018 jpservices@apacer.com

China

Apacer Electronic (Shanghai) Co., Ltd

Room D, 22/FL, No.2, Lane 600, JieyunPlaza, Tianshan RD, Shanghai, 200051, China

Tel: 86-21-6228-9939 Fax: 86-21-6228-9936 sales@apacer.com.cn

U.S.A.

Apacer Memory America, Inc.

46732 Lakeview Blvd., Fremont, CA 94538

Tel: 1-408-518-8699 Fax: 1-510-249-9551 sa@apacerus.com

Europe

Apacer Technology B.V.

Science Park Eindhoven 5051 5692 EB Son, The Netherlands

Tel: 31-40-267-0000 Fax: 31-40-290-0686 sales@apacer.nl

India

Apacer Technologies Pvt Ltd, Unit No.201, "Brigade Corner", 7th Block Jayanagar,

Yediyur Circle, Bangalore - 560082, India

Tel: 91-80-4152-9061 Fax: 91-80-4170-0215 sales india@apacer.com